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P.W.  
2-24-03

PATENT

Customer No. 22,852

Attorney Docket No. 04329.2622

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: )  
Gaku MINAMIHABA, et al. ) Group Art Unit: 2823  
Serial No.: 09/932,943 ) Examiner: Lee, Hsien Ming  
Filed: August 21, 2001 )  
For: SLURRY FOR CHEMICAL )  
MECHANICAL POLISHING AND )  
METHOD OF MANUFACTURING )  
SEMICONDUCTOR DEVICE )

Assistant Commissioner for Patents  
Washington, DC 20231

Sir:

AMENDMENT

In reply to the Office Action dated November 8, 2002, with a period for response extending through February 10, 2003 (February 8<sup>th</sup> being a Saturday), Applicants amend the application as follows, and respectfully request the Examiner's reconsideration in view of the following remarks:

IN THE ABSTRACT:

Please replace the current abstract with the Abstract attached on a separate page. The full text of the Abstract in clean form is as follows:

A method of manufacturing a semiconductor device uses a slurry for chemical mechanical polishing during the manufacturing process, the slurry containing polishing particles comprising colloidal particles whose primary particles have a diameter ranging from 5 to 30 nm,

*Concurred*  
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